



THE WORKSHOP AT A GLANCE

Monday 17 September 2007

- 🕒 8.00 - 9.30
Registration
- 🕒 8.50 - 9.00
Welcome address
- 🕒 9.00 - 9.40
Invited talk 1:
THERMAL CHALLENGES
IN 3-D STACKED
PACKAGING
- 🕒 9.40 - 11.00
Session 1:
TRANSIENT
THERMAL
CHARACTERISATION
- ➔ 11.00 Break
- 🕒 11.20 - 12.40
Session 2:
RELIABILITY
OF SOLDER JOINTS
- ➔ 12.40 Lunch
- 🕒 14.00 - 15.50
Session 3:
MICROSCALE
COOLING
- ➔ 15.50 Break
- 🕒 16.10 - 16.50
VENDOR SESSION
- 🔴 16.50 - 17.30
POSTER
SESSION:
INTRODUCTION
AND VIEWING
- ➔ 18.30 Cocktail

Tuesday 18 September 2007

- 🕒 8.30 - 9.10
Invited talk 2:
HIGH PERFORMANCE
THERMAL INTERFACE
TECHNOLOGY
OVERVIEW
- 🕒 9.10 - 10.30
Session 4:
PROGRESS
IN COMPACT
MODELLING
THEORY
- ➔ 10.30 Break
- 🕒 10.50 - 12.30
Session 5:
ADVANCES
IN COOLING
TECHNOLOGIES
- ➔ 12.30 Lunch
- 🕒 14.00 - 15.40
Session 6:
DEVELOPMENTS
IN EXPERIMENTAL
ANALYSIS
- ➔ 15.40 Break
- 🕒 16.00 - 17.30
PANEL: THERMALLY
INDUCED STRESSES
AND STRAINS
IN ELECTRONIC
INDUSTRY
- ➔ 19.00
Social event: cruise
on the Danube.

Wednesday 19 September 2007

- 🕒 9.00 - 9.40
Invited talk 3:
THERMAL
MANAGEMENT
AND THERMAL
RESISTANCE OF
HIGH POWER LEDs
- 🕒 9.40 - 10.40
Session 7:
MULTI-PHYSICS
SIMULATION
- ➔ 10.40 Break
- 🕒 11.00 - 12.00
Session 8:
PACKAGE
RELIABILITY
- ➔ 12.00 Lunch

International Workshop on THERMAL INvestigations of ICs and Systems

PROGRAMME 2007



Budapest Hungary > 17 - 19 September 2007

The Workshop is sponsored by the IEEE
Components, Packaging, and Manufacturing
Technology Society and by CMP.

in cooperation with

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COMPONENTS, PACKAGING
AND MANUFACTURING
TECHNOLOGY SOCIETY



THERMINIC 2007

Electronic Workshop Registration form
<http://tima.imag.fr/conferences/therminic/>



Registration will be electronically only

Detailed information about the registration process is available on the THERMINIC Web page. Authors should in addition notify their registration to the General Chair Bernard COURTOIS by email (THERMINIC@imag.fr).

Workshop advance registration is applied if participant is registered and the payment is received before 24 August 2007.

Please tick the appropriate:

☐ IEEE Member: IEEE N°	Advance Until 24 August 2007	Late After 24 August 2007	Sub-total
☐ Author: Paper N° Session N°	480 Euros	580 Euros	
☐ Committee Member			
☐ Non-member	580 Euros	690 Euros	
☐ Additional ticket (65 €/each) Cocktail and social event	65 Euros	65 Euros	
☐ Additional Proceedings (35 €/each)	35 Euros	35 Euros	
		TOTAL	€

• Workshop registration fee covers admission to all sessions, coffee breaks, lunches on 17-18-19 September 2007, the social event and the Workshop proceedings.

• For payment by credit card (ADR), follow the registration instruction, you will find it in the payment part.

Return the form to:



Bernard Courtois
CMP

46 Avenue Félix Viallet 38000 Grenoble, France
Fax: +33 4 76 47 38 14

■ Refund policy for preregistration: there is a 80 Euros service charge for processing refunds. Requests for preregistration refunds must be received no later than 6 working days prior to the first day of the Workshop to be honoured. **No refunds will be issued after 06 September 2007.** Substitutions will be accepted at any stage.



INTERNATIONAL WORKSHOP ON THERMAL INVESTIGATIONS OF ICS AND SYSTEMS

Sponsored by the IEEE Components,
Packaging, and Manufacturing Technology
Society and by CMP

AIM OF THE WORKSHOP

THERMINIC Workshops are a series of events to discuss the essential thermal questions of microelectronic microstructures and electronic parts in general. These questions are becoming more and more crucial with the increasing element density of circuits packaged together and with the move to nanotechnology. These trends are calling for thermal simulation, monitoring and cooling. Thermal management is expected to become an increasingly dominating factor of a system's cost. The growing power dissipated in a package, the mobile parts of microsystems raise new thermal problems to be solved in the near future necessitating the regular discussion of the experts in these fields. Finally, there is an increasing need for accurate assessment of the boundary conditions used in the analysis of electronic parts, which requires a concurrent solution of the thermal behaviour of the whole system.

AREAS OF INTEREST

The main topics to be discussed during the Workshop are the following:

- Thermal and Temperature Sensors
- Thermal Simulation
- Electro-thermal Simulation
- Thermal Modelling and Investigation of Packages
- Reliability Issues
- High Temperature Electronics
- Heat Transfer Education
- Flow Visualisation Techniques
- Turbulence Modelling in Complex Geometries
- Defect and failure modelling
- Reliability evolution and prediction
- Multiphysics simulation
- Nanoengineering issues
- Education
- Measurement of Thermal Properties
- Acquisition and analysis of Thermal data
- Temperature Mapping
- Novel and Advanced Cooling Techniques
- Thermal Performance of Interconnects
- Heat Transfer Enhancement
- Validation of Thermal Software
- Coupled (Thermo-mechanical, Thermo-optical, etc.) Effects
- Thermal Stress: Theory and Experiment
- Thermal Stress Failures: Prediction and Prevention
- Nanotechnology Applications.



Previous THERMINIC Workshops have been held in Grenoble [1995], Budapest [1996], Cannes [1997 and 1998], Rome [1999], Budapest [2000], Paris [2001], Madrid [2002], Aix en Provence [2003], Sophia Antipolis Côte d'Azur [2004] and Belgirate [2005] and Nice [2006].



The programme includes 3 invited talks by prominent speakers (see the paragraph below), 33 oral in 8 sessions, oral contributions consist of 15 min. presentations followed by 5 min. discussion, 12 poster presentations, all posters will be introduced by one slide in 3 minutes each in a plenary session.



Budapest – one of the most beautiful cities in the world – has developed where it is, is not down to some historical accident. Take a look at Gellért Hill, right next to the River Danube as it flows majestically through the centre of the modern city. It was precisely the combination of the relative ease of crossing the River here and the natural protection the hill offered against invasion that decided the earliest settlers it was the ideal place to build a town. The Eravisci, a tribe of highly cultured Celts, had already settled at Gellért Hill in the third and fourth centuries B.C. They worked with iron, decorated their earthenware pots and even minted their own coins. Later, the Romans built a settlement at today's Óbuda. They called it Aquincum and it was an important station along the limes which ran alongside the River Danube.



LOCATION

The Workshop will take place in the Danubius Gellért Hotel.
Danubius Hotel Gellert is one of the most traditional hotels in Budapest and Hungary.

The hotel was erected on the right bank of the River Danube between 1916 and 1918 until its opening to the public on September 24th, 1918 and has maintained the highest recognition ever since. Next to the hotel you can find the world famous Gellert Bath. Danubius Hotel Gellert Budapest is located in a picturesque environment at the foot of Gellert Hill, on the bank of the Danube, is ideally situated for both business and leisure travellers. This impressive location is within walking distance to Budapest's most fashionable shopping and business district with one of the most beautiful sights of Budapest, the Liberty Bridge.

DANUBIUS HOTEL GELLERT

Szent Gellért tér, 1Budapest H-1111, Hungary
Phone: +36 1 8895500 – Fax: +36 1 8895505
<http://www.danubiushotels.com/gellert>



SOCIAL EVENT ON 18 SEPTEMBER 2007

The Danube is celebrated as Europe's greatest river. It is a river of great beauty and importance flowing through central and southeastern Europe, as well as, the Balkans and the Black Sea. It has been the inspiration of music, novels and poems. Nine countries share its waters, including Germany, Austria, Slovakia, Hungary, Yugoslavia, Serbia, Bulgaria, Croatia, Romania, and Hungary. Danube at Budapest it is dominating the city, separating it to Buda and Pest.

Our cruise will start in the evening, showing some of the most important monuments of Budapest, like the Hungarian Academy of Sciences, The House of Parliament, the beautiful bridges, the major universities, the National Theater, the new Concert Hall, the traditional old hotels, etc. As the sun goes down the city changes gradually and become s truly captivating with the sophisticated illumination of the buildings that the cruisers can enjoy besides a nice diner and good wines.

General Chair Vice General Chair Programme Chairs

- > **B. Courtois**, CMP, Grenoble, France
- > **M. Rencz**, BUTE, Budapest, Hungary
- > **C. Lasance**, Philips, Eindhoven, The Netherlands
- > **V. Székely**, BUTE, Budapest, Hungary

PROGRAMME COMMITTEE

- | | |
|---|--|
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| B. Charlot , TIMA- CMP, France & LIMMS, Tokyo, Japan | M-W. Shin , Myong Ji Univ., Korea |
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| Y. Scudeller , Ecole Polytechnique Univ. Nantes, France | M-N. Sabry , Univ. Française d'Égypte/Egypt |
| | H. Pape , Infineon Techn./Germany |

SPECIAL ISSUES AND SPECIAL SECTIONS

of leading periodicals have been organised regarding the previous Workshops [Journal of Sensors and Actuators, Microelectronics Journal, IEEE Transactions on VLSI Systems, IEEE Transactions on Components and Packaging Technologies, Journal of Electronic Packaging]. It is again expected to have special issues and special sections of leading periodicals as follow up of the Workshop 2007.

INFORMATION

More information on the Workshop is available from:

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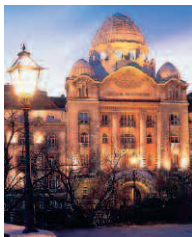


An exhibition will be held during the time of the Workshop. Tabletops or Spaces for a portable marketing stand 6sqm are available to companies interested to exhibit equipment, materials, software, etc. Booking of each table-top or Spaces for a portable marketing stand 6sqm will give one slot of time during the vendors' session. The number of spaces is limited. They will be offered on a first signed - first served basis. Contact the General Chair for more information.



HOTEL INFORMATION

Hotel Gellért Budapest has offered a package deal for THERMINIC 2007. Please book early, the allocation and special rates are subject to availability. Delegates must arrange their accommodation directly with Hotel Gellért Budapest. Reservation deadline: 24 August 2007. For hotel details please visit the following web page: <http://www.danubiushotels.com/gellert>



PROCEEDINGS

of this Workshop will be available at the meeting as part of the registration fee. If you cannot attend, you may still order Proceedings at the price of 35€ (order form available on the conference web site, the sending of the Proceedings package will be done after the Workshop, and if the payment is received).

THERMINIC is happy to acknowledge the services of SuviSoft Oy Ltd for the technical management of the Workshop.



SPECIFIC EVENTS SPONSORING

If you wish to sponsor an event like a reception, a lunch, or any specific event during the Workshop, please contact the General Chair.



POSTERS

All posters will be introduced by one slide in 3 minutes each. They will be presented in one session on 18 September from 16:50 to 17:29. They will be mounted during the registration. Authors are expected to be at their posters during the posters viewing session just after the introduction session on 18 September. The posters will be removed by the end of the Workshop.

→ THERMAL CHALLENGES IN 3-D STACKED PACKAGING

→ Venkat Natarajan, Intel India Pvt. Ltd., Bangalore, India

Emerging Trends in electronics industry has led to the rapid development of 3-D stacked packaging technology. 3-D packages offer compactness in form factors with significant benefits in performance. The present talk will define key thermal challenges in enabling 3-D stacked packaging technology. Both component-level and system-level challenges will be discussed for the computing platform. Potential research opportunities/directions in the field of heat transfer for 3-D technologies will be presented. Results from on-going heat transfer research on 3-D stacks (P-O-P) at Intel will be presented.

→ HIGH PERFORMANCE THERMAL INTERFACE TECHNOLOGY OVERVIEW

→ Bruno Michel, IBM Zurich Research Laboratory, Rueschlikon, Switzerland

An overview on recent developments of thermal interfaces will be given with a focus on a novel thermal interface technology that allows formation of 2-3 times thinner bondlines with much better thermal properties at lower assembly pressures. This is achieved using a nested hierarchical surface channels to control of particle stacking with highly particle-filled materials. Thermal cycling demonstrates a decrease in thermal resistance over time and longer overall lifetimes.

→ THERMAL MANAGEMENT AND THERMAL RESISTANCE OF HIGH POWER LEDs

→ Thomas Zahner, OSRAM Opto Semiconductors, Regensburg, Germany

The junction temperature of Light Emitting Diodes (LEDs) is a primary reliability parameter. Exceeding the maximum rated junction temperature could lead to accelerated light output degradation and sometimes even to catastrophic failures. Besides that junction temperature influences the desired LED properties in applications like light output efficiency, dominant wavelength and forward voltage. Therefore thermal management and proper thermal characterisation of high power LEDs is very important for a reliable product with good performance. By measuring the thermal resistance of a high power LED it has to take into account that the power applied to the device is converted into heat and light (~20-40% efficiency). This means that the thermal resistance of a LED can not be determined without knowing the energy flux emitted as light. Therefore in general the interpretation of a given thermal resistance of an optoelectronic device is not well defined. Establishing of a standard on how to do thermal resistance measurement for light emitting devices is necessary.

08:00 - 09:00 Registration

08:50 - 09:00 Welcome address

Bernard Courtois, CMP, Grenoble, France
Márta Rencz, Budapest Univ. of Technology and Economics (BUTE), Hungary

09:00 - 09:40 Invited talk I: THERMAL CHALLENGES IN 3-D STACKED PACKAGING

Venkat Natarajan, Intel India, Bangalore, India
Chair: Clemens Lasance, Philips Research Laboratories, Eindhoven, The Netherlands

09:40 - 11:00 Session I: TRANSIENT THERMAL CHARACTERISATION

Chair: TBA

09:40 APPLICATION OF STRUCTURE FUNCTIONS FOR THE INVESTIGATION OF FORCED AIR COOLING

Marcin Janicki, Marek Kaminski, Andrzej Napieralski, Technical Univ. of Lodz, Poland
Jedrezy Banaszczyk, Gilbert De Mey, Bjorn Vermeersch, Ghent Univ., Belgium

10:00 UTILITY OF TRANSIENT THERMAL TESTING TO CHARACTERIZE THERMAL INTERFACE MATERIALS

Brian Smith, Thomas Brunschweiler, Hugo Rothuizen, Bruno Michel, IBM Research, Switzerland

10:20 SHORT TIME DIE ATTACH CHARACTERISATION OF SEMICONDUCTOR DEVICES

Peter Szabo, Márta Rencz, Budapest Univ. of Technology and Economics, Hungary

10:40 METHOD OF IMAGES FOR THE FAST CALCULATION OF TEMPERATURE DISTRIBUTIONS IN PACKAGED VLSI CHIPS

Virginia Martin Heriz, Je-Young Park, Travis Kemper, Sung-Mo Kang, Ali Shakouri, UCSC, USA

11:00 - 11:20 COFFEE BREAK

11:20 - 12:40 Session 2: RELIABILITY OF SOLDER JOINTS

Chair: TBA

11:20 NEW RELIABILITY ASSESSMENT METHOD FOR SOLDIER JOINTS IN BGA PACKAGE BY CONSIDERING THE INTERACTION BETWEEN DESIGN FACTORS

Satoshi Kondo, Qiang Yu, Tadahiho Shibutani, Masaki Shiratori, Yokohama National Univ., Japan

11:40 EVALUATION TECHNIQUE FOR THE FAILURE LIFE SCATTER OF LEAD-FREE SOLDER JOINTS IN ELECTRONIC DEVICE

Hiroki Miyauchi, Qiang Yu, Tadahiho Shibutani, Masaki Shiratori, Yokohama National Univ., Japan

12:00 EVALUATION OF THE IMPACT OF SOLDER DIE ATTACH VERSUS EPOXY DIE ATTACH IN A STATE OF THE ART POWER PACKAGE

Julia Czernohorsky, Bartosz Maj, Matthias Viering, Continental Automotive Systems, Germany
Lance Wright, Gerry Balanon, Texas Instruments, USA

12:20 THE CHARACTERISTICS OF ELECTROMIGRATION AND THERMOMIGRATION IN FLIP CHIP SOLDER JOINTS

Dan Yang, Y.C. Chan, Department of Electronic Engineering, City Univ. of Hong Kong, Hong Kong

12:40 - 14:00 LUNCH

14:00 - 15:50 Session 3: MICROSCALE COOLING

Chair: TBA

14:00 DEVELOPMENT OF EHD ION-DRAG MICROPUMP FOR MICROSCALE ELECTRONICS COOLING SYSTEMS

Anthony Robinson, Trinity College Dublin, Ireland

14:30 NUMERICALLY INVESTIGATING THE EFFECTS OF CROSS LINKS IN SCALED MICROCHANNEL HEAT SINKS

Minh N Dang, Ibrahim G Hassan, Sung In Kim, Concordia Univ., Canada

14:50 COPPER-FILLED MACROPOROUS SI FOR MICROCHANNEL HEAT SINK TECHNOLOGY

Filimon Zacharatos, Androula Nassiopoulou, IMEL, NCSR "Demokritos", Greece

15:10 DEPENDENCY OF HEAT TRANSFER RATE ON THE BRINKMAN NUMBER IN MICROCHANNELS

Heesung Park, Stoke's Institute, Univ. of Limerick, Ireland

15:30 A NOVEL VLSI TECHNOLOGY TO MANUFACTURE HIGH-DENSITY THERMOELECTRIC COOLING DEVICES

Howard Chen, Louis Hsu, Xiaojin Wei, IBM, USA

15:50 - 16:10 COFFEE BREAK

16:10 - 16:50 Vendor session

Chair: Bernard Courtois, CMP, Grenoble, France

16:50 - 17:30 Poster session: introduction and viewing

Chair: Márta Rencz, Budapest Univ. of Technology and Economics, Hungary

The posters will be introduced by one slide in maximum 3 minutes each.

16:50 DEVELOPMENT OF THE MICRO CAPILLARY PUMPED LOOP FOR ELECTRONIC COOLING

Seok-Hwan Moon, Electronic Telecommunication Research Institute, South Korea

16:53 THERMAL AND MECHANICAL ANALYSIS OF HIGH POWER LEDS WITH CERAMIC PACKAGES

Jianzheng Hu, Lianqiao Yang, Moo Whan Shin, Myongji Univ., South Korea

16:56 VERY FAST CHIP-LEVEL THERMAL ANALYSIS

Keiji Nakabayashi, Nara Institute of Science and Technology, Japan
Tamiyo Nakabayashi, Nara Women's Univ., Japan
Kazuo Nakajima, Univ. of Maryland, USA

16:59 INVESTIGATION OF MICRO POROSITY SINTERED WICK IN VAPOR CHAMBER FOR FAN LESS DESIGN

Chun Sheng Yu, Tamkang Univ., Taiwan

17:02 STUDY OF WATER SPEED SENSITIVITY IN A MULTIFUNCTIONAL THICK-FILM SENSOR BY ANALYTICAL THERMAL SIMULATIONS AND EXPERIMENTS

Fabio Stefani, Paolo Emilio Bagnoli, Univ. of Pisa, Italy
Stefano Luschi, AMIC srl, Italy

17:05 ADVANCEMENT OF MULTIFUNCTIONAL SUPPORT STRUCTURE TECHNOLOGIES (AMFSS)

Ralf John, HTS GmbH, Germany
Garbine Atxaga, INASMET-Tecnalia, Spain
Hap Jens Frerker, OHB-Systems AG, Germany
Alfred Newerla, ESA/ESTEC, Netherlands

17:08 NON-DESTRUCTIVE FAILURE ANALYSIS AND MODELLING OF ENCAPSULATED MINIATURE SMD CERAMIC CHIP CAPACITORS USING THERMAL AND MECHANICAL LOADING

Bernhard Wunderle, Daniel May, Tanja Braun, Hans Walter, Karl-Friedrich Becker, Bernd Michel, Fraunhofer IZM, Germany
Herbert Reichl, Technische Universität Berlin, Germany

17:11 TRANSIENT NON-LINEAR THERMAL FEM SIMULATIONS OF SMART

Vladimir Kosel, KAI GmbH, Austria

17:14 COMBINATION OF THERMAL SUBSYSTEMS MODELLED BY RAPID CIRCUIT TRANSFORMATION

York Christian Gerstenmaier, Siemens AG, Corporate Technology, Germany
Gerhard Wachutka, Munich Univ. of Technology, Germany

17:17 A NOVEL THERMAL POSITION SENSOR INTEGRATED ON A PLASTIC SUBSTRATE

Anastasios Petropoulos, NCSR "Demokritos", Greece
Grigoris Kaltsas, TEI Athens, Greece
Androula Nassiopoulou, NCSR "Demokritos", Greece

17:20 INFLUENCE OF TRANSPARENT SURFACE LAYER ON EFFECTIVE THERMOREFLECTANCE COEFFICIENT OF TYPICAL STACKED ELECTRONIC STRUCTURES

Pavel Komarov, Mihai Burzo, Peter Raad, SMU, USA

17:23 DYNAMIC THERMOELECTRIC DEVICE SPICE MODEL FOR TRANSIENT COOLING ANALYSIS

Daniel Mitrani, Jordi Salazar, Antoni Turó, Miguel J. García, Juan A. Chávez, Catalonia Technical Univ., Spain

18:30 COCKTAIL

Notes



08:30 - 09:10 Invited talk 2: HIGH PERFORMANCE THERMAL INTERFACE TECHNOLOGY OVERVIEW

Bruno Michel, IBM Zurich Research Laboratory, Rueschlikon, Switzerland
Chair: Vladimír Székely, Budapest Univ. of Technology and Economics, Hungary

09:10 - 10:30 Session 4: PROGRESS IN COMPACT MODELLING THEORY

Chair: TBA

09:10 THERMAL NETWORKS FROM PHONON BOLTZMANN'S TRANSPORT EQUATION: PART I - FUNDAMENTALS

Lorenzo Codecasa, Politecnico di Milano, Italy

09:30 THERMAL NETWORKS FROM PHONON BOLTZMANN'S TRANSPORT EQUATION: PART II - COMPACT MODELING

Lorenzo Codecasa, Politecnico di Milano, Italy

09:50 FLEXIBLE PROFILE APPROACH TO THE CONJUGATE HEAT TRANSFER PROBLEM

Mohamed-Nabil SABRY, Universite Francaise d'EGYPTE, Egypt

10:10 A NEW METHODOLOGY FOR EXTRACTION OF DYNAMIC COMPACT THERMAL MODELS

Wassim Habra, Patrick Tounsi, Francesc Madrid, LAAS, France
Philippe Dupuy, Freescale Semiconductor, France
Jean-Marie Dorkel, LAAS, France

10:30 - 10:50 COFFEE BREAK

10:50 - 12:30 Session 5: ADVANCES IN COOLING TECHNOLOGIES

Chair: TBA

10:50 ACOUSTICALLY ENHANCED BOILING HEAT TRANSFER

Ari Glezer, Zach Douglas, Marc Smith, Georgia Tech, USA

11:10 CONTROLLED POOL-BOILING SYSTEMS: A WAY FOR HIGH-PERFORMANCE COOLING SCHEMES?

Michel Speetjens, Eindhoven Univ. of Technology, Netherlands

11:30 FULLY INTEGRATED ONE PHASE LIQUID COOLING SYSTEM FOR ORGANIC BOARDS

Daniel May, Fraunhofer IZM, Germany

11:50 DEVELOPMENT OF A PROTOTYPE THERMAL MANAGEMENT SOLUTION FOR 3-D STACKED CHIP ELECTRONICS BY INTERLEAVED SOLID SPREADERS AND SYNTHETIC JETS

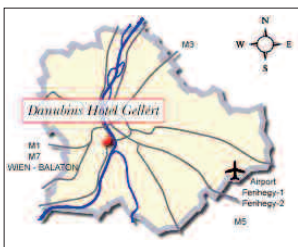
David Gerlach, Donavon Gerty, Yogendra Joshi, Ari Glezer, Georgia Institute of Technology, USA

12:10 EVALUATION OF COOLING SOLUTIONS FOR OUTDOOR ELECTRONICS

Mahendra Wankhede, S. D. Mahajan, PIET's College of Engineering, India
Vivek Khaire, Avijit Goswami, Applied Thermal Technologies India, India

12:30 - 14:00 LUNCH





BY AIR

Budapest is very conveniently reachable by air. All the major European airlines have several flights a day to Budapest Airport that is an about 30 min drive from the Hotel Gellert. MALEV Hungarian Airlines is member of the one world alliance offering services all around the world. More information at:
http://www.budapestinfo.hu/en/general_information/getting_here

Notes



ACCOMMODATION BOOKING FORM

Ref: THERMINIC Workshop, 17-19 September 2007

Hotel Gellért Budapest has offered a package deal for THERMINIC 2007. Please book early, the allocation and special rates are subject to availability. Delegates must arrange their accommodation directly with

Hotel Gellért Budapest

Reservation deadline: 24 August 2007

For hotel details please visit the following web page: danubiushotels.com/gellert

Type A: Single room with bath (courtyard view) EUR 104/room/night, breakfast, VAT and access to the thermal baths on site included

Type B: Double room (courtyard view) EUR 136/room/night, breakfast, VAT and access to the thermal baths on site included

Guest details			<i>Please complete one form per room</i>		
First name of Delegate(s):					
Last name:					
Organization:					
Address (street, post code, city, country):					
Tel. No:			Fax. No.:		
E-mail:					
Arrival Date:		Departure Date:		No. of Nights:	
Room type (A, B):		Number of adults in the room:			
Credit Card:					
Number:					
Exp. Date:		Card verification value: (please type the 3 last numbers that are on the back of your card)			
Card Holders Name:					
Signature					

Booking / payment information

1. Cancellation deadline for the reservation is 3 days prior to arrival
2. In case of no-show or late cancellation your credit card will be charged with 1 night cost.
3. Check-in time: from 2 PM, check-out: until 12 AM (noon)
4. We cannot guarantee hotel accommodation will be available for request made after **24 August 2007**.

Confirmation from Hotel Gellért (please leave blank)
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Mail/fax this form as soon as possible to HOTEL GELLÉRT BUDAPEST at:

HOTEL GELLÉRT BUDAPEST
H-1111 Budapest, Szent Gellért tér 1, Hungary
Telephone: +36 1 889-5500 - Fax: +36 1 889-5505
Email: gellert.reservation@danubiusgroup.com